

ABSTRACT OF THE DISCLOSURE

A ceramic heater capable of reducing temperature uniformity at the periphery of through holes such as insertion holes and vacuum suction holes is provided, which protects wafer against thermal shocks and has improved controllability for temperature control parts such as thermocouples and temperature fuse. Further, a ceramic heater capable of uniform resin curing is provided. A heat generation body is disposed on the surface or inside of a ceramic substrate. Further, corners for the insertion holes, the recesses and the vacuum suction holes of the ceramic substrate are chamfered.